Winner of the
productronica
innovation award 2021

Cluster Semiconductors – AP&S International GmbH

CleanSurF

The new AP&S CleanSurF® cleaner ensures the cleanliness of all these standardized wafer transport containers like FOUPs, SMIFs, carriers and boxes in accordance with highest purity standards to secure the process chains in semiconductor manufacturing and ensure maximum productivity. High throughput, optimum cleaning performance, maximum flexibility in use and attractive operating costs are the advantages of the new cleaning machine. The special feature of the CleanSurF® product concept is that the cleaner is designed for both manual and automatic loading. It can also be connected to a FOUP stacker for cleaning during intermediate storage of the containers.

Tobias Bausch, CMO & CTO:
"During product development, the following considerations were decisive for us: We wanted to develop a cleaner according to the latest technical standard, which enables both manual and automatic loading and increases the capacity of our existing cleaners. Our goal - to realise a system with efficient throughput and attractive TCO - has been achieved with our new CleanSurF®."

About AP&S International

AP&S International is a leading provider of chemical wet process equipment for the semiconductor industry. Among our customers are market-leading manufacturers of microchips, MEMS and optoelectronics worldwide. Characteristic for our machines are: high throughput, superior process performance, attractive TCO values and maximum flexibility (bridge tools and customized solutions). Our portfolio includes batch and single wafer equipment including manual, semi-automated and fully automated wet process machines as well as production supporting equipment like cleaners for FOUP, SMIF and boxes, laboratory equipment and chemical management systems. AP&S processing tools cover all common chemical wet processes used in semiconductor production chains, such as cleaning, etching, stripping, plating, developing, metal etching, e-less plating, lift-off and drying. Our equipment handles masks and wafers up to 300mm including different substrate thicknesses and wafer materials like silicium Si, silicium carbid SiC, gallium nitrid GaN, gallium arsenid GaAs, sapphire, glass. The AP&S headquarters is located in Donaueschingen, Germany. The company's subsidiaries are in China, Singapore and Malaysia.
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